

Electronic Patent Application Fee Transmittal

Application Number:	10721382			
Filing Date:	26-Nov-2003			
Title of Invention:	High density chip scale leadframe package and method of manufacturing the package			
First Named Inventor/Applicant Name:	Hien Boon Tan			
Filer:	Carl Joseph Pellegrini/ruth swanson			
Attorney Docket Number:	Q78432			
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Utility under 35 USC 111(a) Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Filing a brief in support of an appeal	1402	1	540	540
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				540